

Excellent Integrated System Limited

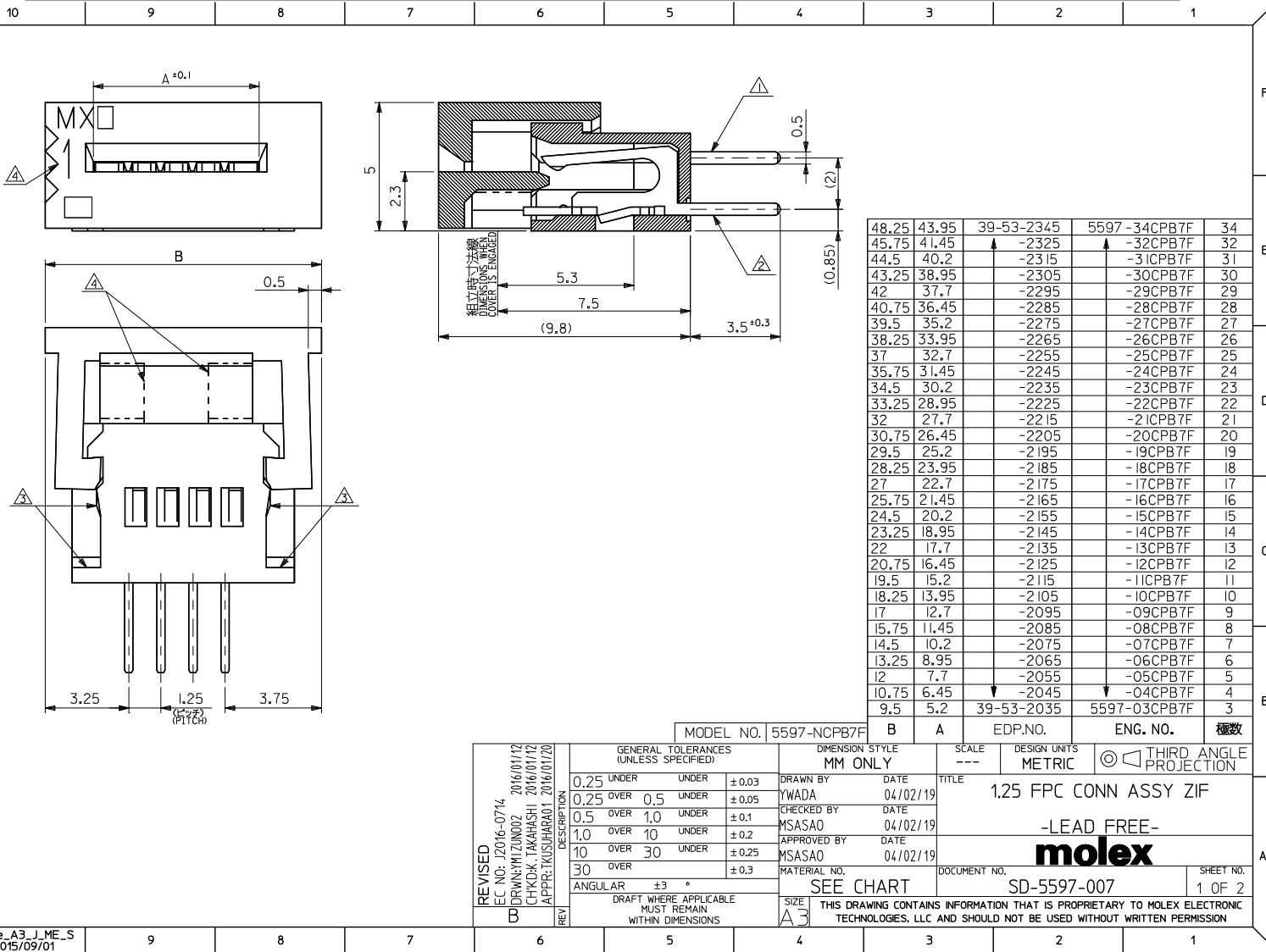
Stocking Distributor

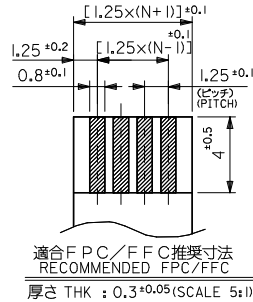
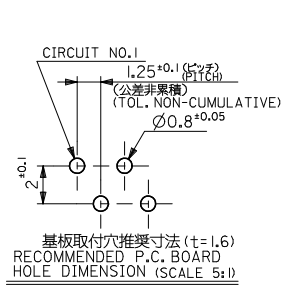
Click to view price, real time Inventory, Delivery & Lifecycle Information:

[Molex Connector Corporation](#)
[0039532115](#)

For any questions, you can email us directly:

sales@integrated-circuit.com





FPCについて:

打抜き方向は導体側から補強板側を推奨いたします。
補強フィルム材質はポリイミドを推奨致します。
接着剤は熱硬化接着剤を推奨致します。

ABOUT FPC:

RECOMMENDED PUNCHER DIRECTION :
FROM CONDUCTOR SIDE TO STIFFENER BOARD SIDE.
RECOMMENDED MATERIAL:
STIFFENER FILM : POLYIMIDE
BONDING AGENT : THERMOSETTING BONDING AGENT

注記 NOTES

- △ MX J側を基準に奇数番目の極におけるソルダーテール。
SOLDER TAIL OF ODD CKTS, MXJ MARK AS BASIC.
- △ MX J側を基準に偶数番目の極におけるソルダーテール。
SOLDER TAIL OF EVEN CKTS, MXJ MARK AS BASIC.
- △ 3極~10極に適用。APPLY FOR 3-10 CKTS.
- △ 3極~19極に適用。APPLY FOR 3-19 CKTS.
5. () 内寸法は、参考値。
() DIMENSION IS FOR REFERENCE.
6. ソルダーテールは、先端が取付推奨穴にガイドされること。
SOLDER TAILS MAY BE CHECKED BY INSERTION
FOR RECOMMENDED PCB BOARD HOLES.

7. 使用材料
MATERIAL

ハウジング、アクチュエーター: PBTP, UL94V-0
HOUSING, ACTUATOR: PBTP, UL94V-0
ターミナル: リン青銅 (t=0.3)
PHOSPHOR BRONZE (t=0.3)
銅ビスマスマメッキ 1.0µm MIN.
TIN-BISMUTH 1.0 MICROMETER MIN.
ニッケル下地 1.0µm MIN.
NICKEL 1.0 MICROMETER MIN.

8. 本製品は5597-NCPBの鉛フリー品である。
THIS PRODUCT IS LEAD FREE OF 5597-NCPB.

REVISED	EC NO.	J2016-0714	DRAWN BY	DATE	CHECKED BY	DATE	APPROVED BY	DATE	MATERIAL NO.	DOCUMENT NO.	SHEET NO.
REV	01	01	YWADA	04/02/19	MSASAO	04/02/19	MSASAO	04/02/19	SEE CHART	SD-5597-007	2 OF 2
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